

## MOSFET Silicon N-Channel MOS

### 1. Applications

Single-ended flyback or two-transistor forward topologies.  
PC power, PD Adaptor, LCD & PDP TV and LED lighting.



### 2. Features

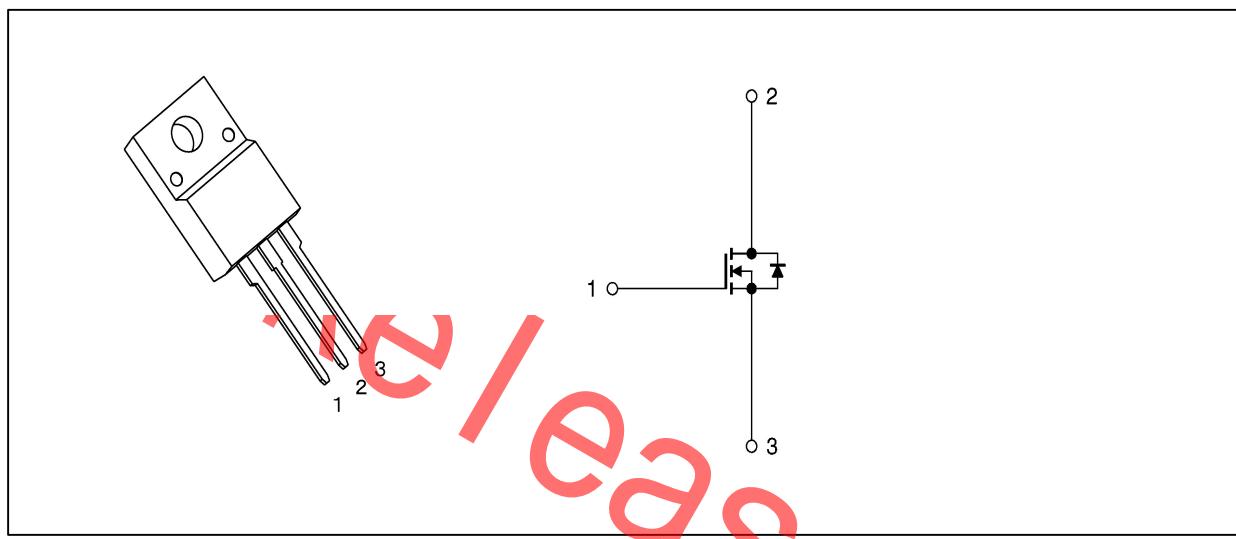
Low drain-source on-resistance:  $R_{DS(ON)} = 0.211\Omega$  (typ.)  
Easy to control Gate switching  
Enhancement mode:  $V_{th} = 2.8$  to  $4.2$  V



**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	750	V
$R_{DS(on),max}$	240	$m\Omega$
$Q_{g,typ}$	32.23	nC
$I_{D,pulse}$	60	A

### 3. Packaging and Internal Circuit



## 1 Maximum ratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$		-	20	A	$T_C=25^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,\text{pulse}}$	-	-	60	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	898	mJ	
MOSFET dv/dt ruggedness	dv/dt	-	-	69	V/ns	$V_{DS}=0\ldots 400\text{V}$
Gate source voltage (static)	$V_{GS}$	-20	-	20	V	static;
Gate source voltage (dynamic)	$V_{GS}$	-30	-	30	V	AC ( $f > 1 \text{ Hz}$ )
Power dissipation	$P_{\text{tot}}$	-	-	33	W	$T_C=25^\circ\text{C}$
Storage temperature	$T_{\text{stg}}$	-55	-	150	°C	
Operating junction temperature	$T_j$	-55	-	150	°C	
Reverse diode dv/dt <sup>3)</sup>	dv/dt	-	-	15	V/ns	$V_{DS}=0\ldots 400\text{V}, I_{SD} \leq 48\text{A}, T_j=25^\circ\text{C}$ see table 8

<sup>1)</sup>Limited by  $T_{j,\text{max}}$ . Maximum Duty Cycle D = 0.50

<sup>2)</sup>Pulse width  $t_p$  limited by  $T_{j,\text{max}}$

<sup>3)</sup>Identical low side and high side switch with identical  $R_G$

re/ease

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	3.8	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	80	°C/W	device on PCB, minimal footprint

Release

### 3 Electrical characteristics

at  $T_j=25^\circ\text{C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	705	-	-	V	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=10\text{mA}$
Gate threshold voltage	$V_{(\text{GS})\text{th}}$	2.8		4.2	V	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$
Zero gate voltage drain current	$I_{\text{DSS}}$	-	-	100	nA	$V_{\text{DS}}=700\text{V}, V_{\text{GS}}=0\text{V}, T_j=25^\circ\text{C}$
Gate-source leakage current	$I_{\text{GSS}}$	-	-	100	nA	$V_{\text{GS}}=30\text{V}, V_{\text{DS}}=0\text{V}$
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	-	0.211	0.24	$\Omega$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}, T_j=25^\circ\text{C}$
Gate resistance (Intrinsic)	$R_{\text{G}}$	-	11.1	-	$\Omega$	$f=1\text{MHz}$ , open drain

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{\text{iss}}$	-	1547	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Output capacitance	$C_{\text{oss}}$	-	134	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Reverse transfer capacitance	$C_{\text{rss}}$	-	5.28	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Turn-on delay time	$t_{\text{d}(\text{on})}$	-	12.4	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=8\text{A}, R_{\text{G}}=3.4\Omega$ ; see table 9
Rise time	$t_{\text{r}}$	-	21.6	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=8\text{A}, R_{\text{G}}=3.4\Omega$ ; see table 9
Turn-off delay time	$t_{\text{d}(\text{off})}$	-	52	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=8\text{A}, R_{\text{G}}=3.4\Omega$ ; see table 9
Fall time	$t_{\text{f}}$	-	18.8	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_{\text{D}}=8\text{A}, R_{\text{G}}=3.4\Omega$ ; see table 9

**Table 6 Gate charge characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{\text{gs}}$	-	8.242	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=8\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate to drain charge	$Q_{\text{gd}}$	-	10.85	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=8\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate charge total	$Q_{\text{g}}$	-	32.23	-	nC	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=8\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate plateau voltage	$V_{\text{plateau}}$	-	5.7	-	V	$V_{\text{DD}}=400\text{V}, I_{\text{D}}=8\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$

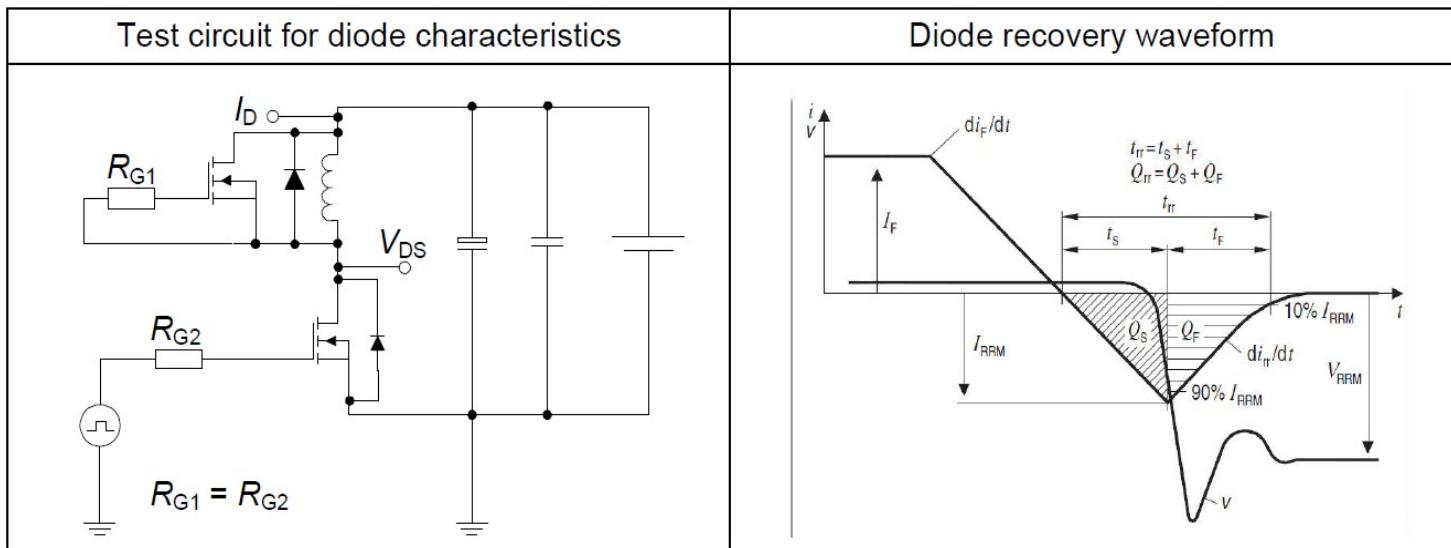
**Table 7 Reverse diode characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$	-	0.72	-	V	$V_{GS}=0V$ , $I_F=1A$ , $T_j=25^\circ C$
Reverse recovery time	$t_{rr}$	-	275	-	ns	$V_R=400V$ , $I_F=8 A$ , $di_F/dt=100A/\mu s$ ; see table 8
Reverse recovery charge	$Q_{rr}$	-	3.809	-	uC	$V_R=400V$ , $I_F=8 A$ , $di_F/dt=100A/\mu s$ ; see table 8
Peak reverse recovery current	$I_{rrm}$	-	25.6	-	A	$V_R=400V$ , $I_F=8 A$ , $di_F/dt=100A/\mu s$ ; see table 8

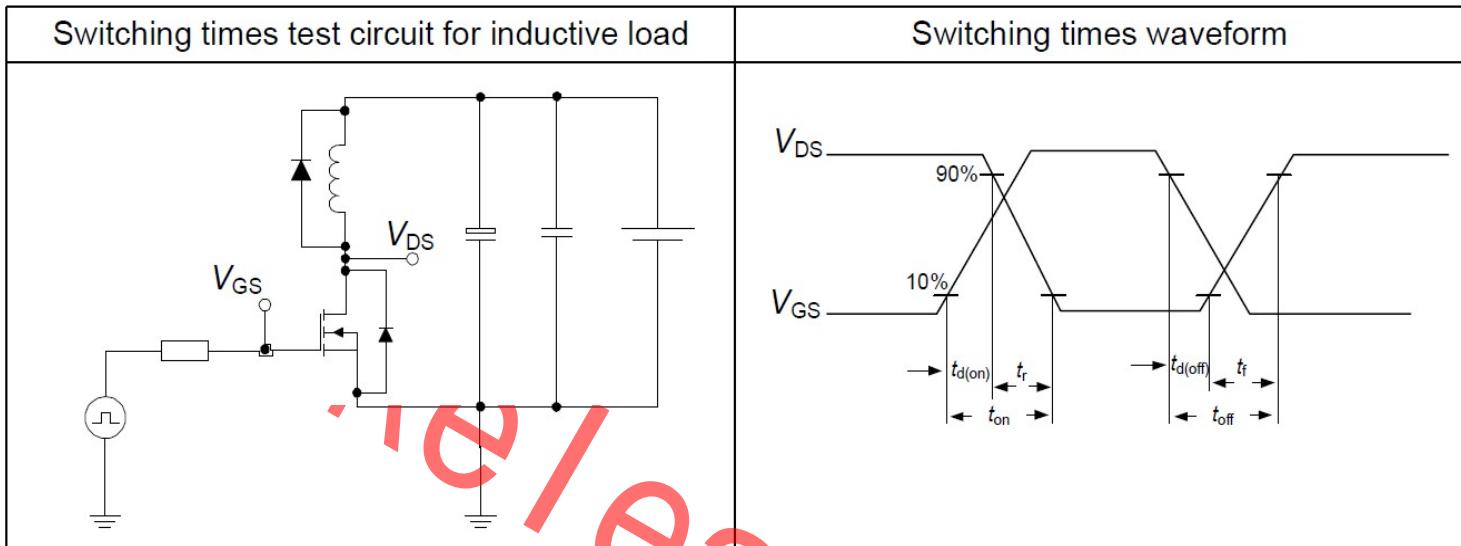
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## 4 Test Circuits

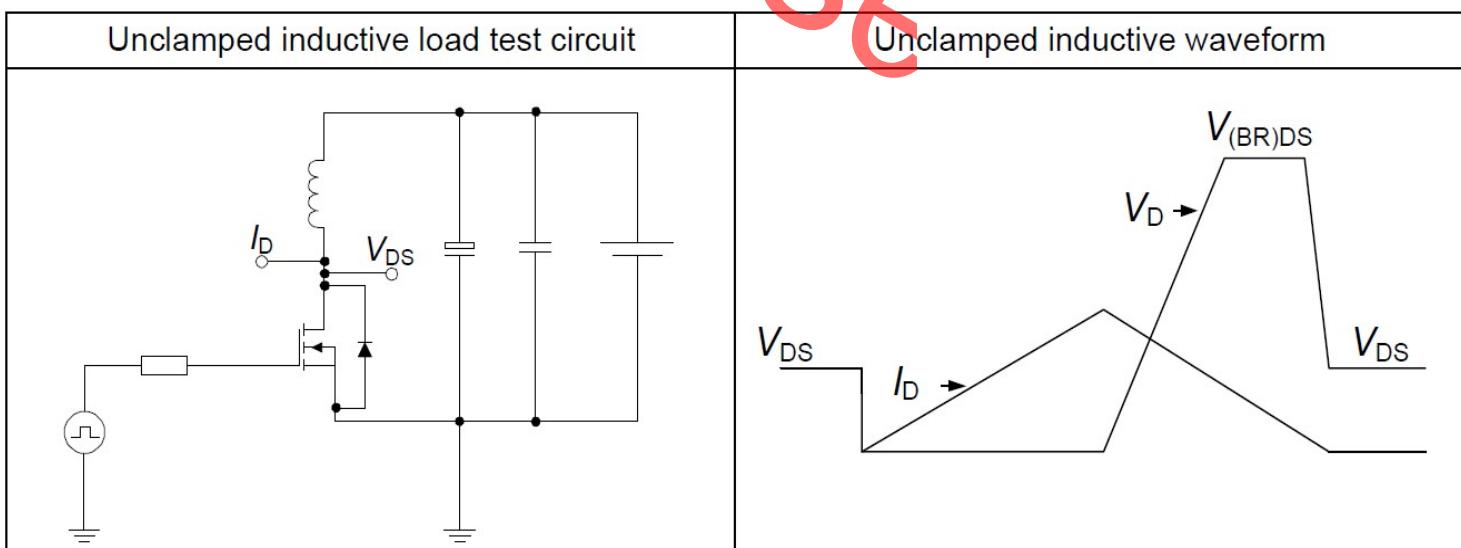
**Table 8 Diode characteristics**



**Table 9 Switching times**



**Table 10 Unclamped inductive load**



## 5 Package Outlines

T□-220F

单位: mm

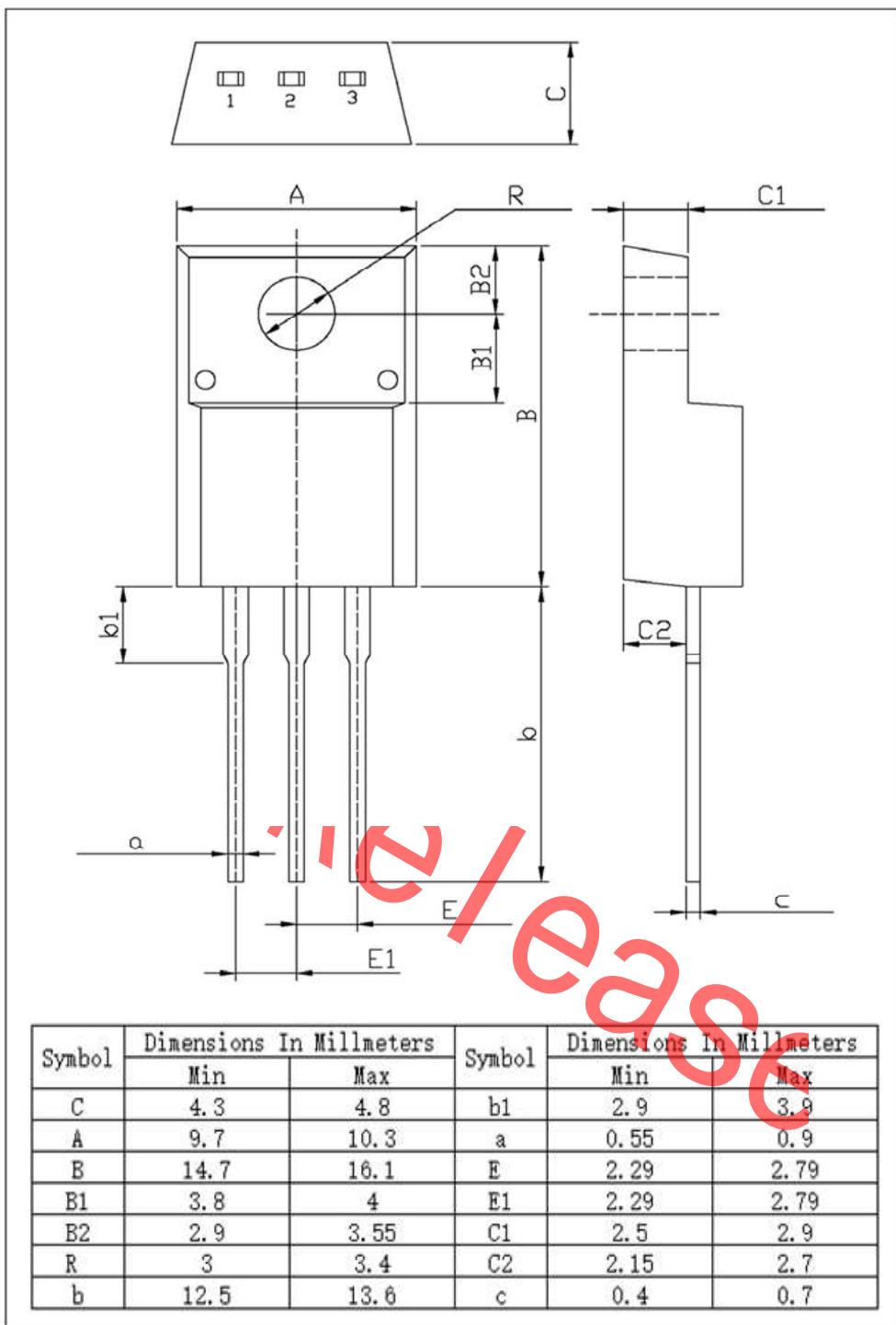


Figure1: Outline PG-T0220F

**Revision History****ASA70R240E**

Revision	Date	Subjects (major changes since last revision)
0.1	2019-5-08	Preliminary version
1.0	2019-11-07	Fine tune outline and add Crss test data.etc

release